

Components, Packaging, and Manufacturing Technology Society



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President's Column.....



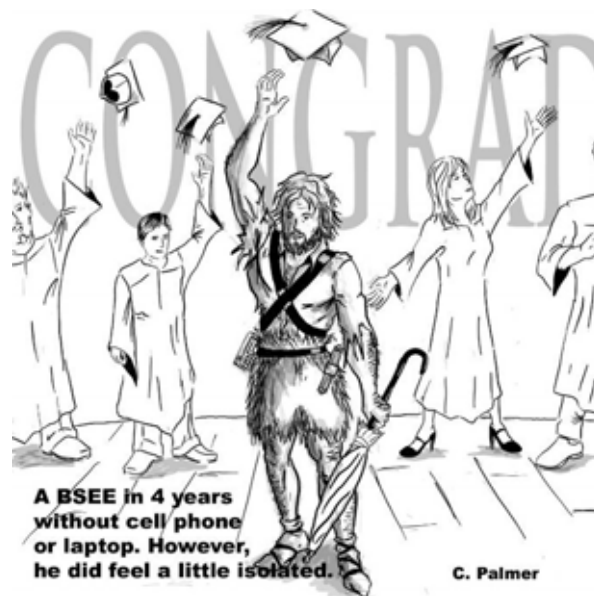
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The summer President's message usually is about ECTC, and this year is not an exception. Many of you have received the email "2009 ECTC Highlights" from Rao Bonda. It brought back vividly memories of the exciting 59th ECTC conference at San Diego. Prior to the conference we had concerns with the conference programs and participation. The worldwide recession had reduced the travel budget in many companies. For participants from Asia there were travel restrictions due to concern with H1N1 influenza. In Rao Bonda's ECTC highlight message he clearly showed that despite these impacts, the 59th ECTC was outstandingly successful. We missed seeing many of you, but we are happy to meet the many who managed to come against all odds.

CPMT technical conferences, such as ECTC, are the Town Hall and Main Street of our profession. We come from around the globe, as a community of professionals, to present our technical findings and to learn the latest in our technologies. Along the hallways, between sessions, during breakfasts and coffee breaks, we meet old friends and make new ones, touching base on the happenings in industry, research facilities, and universities. The conferences are global network centrals for our profession. In these trying times keeping up with the network is of crucial importance for all of us.

With a good balance between contributions from industry, research institutions, and academia, ECTC technical programs provided excellent insight on what would soon become high volume production in the market place as well as to what might be happening three to five years out. From 3D Packaging - TSV, nano materials, optoelectronics, flip chip and wirebond, reliability, materials processing and materials science and emerging technologies, there was a surfeit of interesting and important work to listen and learn. It took some good study of the technical program not to miss what I wanted to attend. Usually the day started with technical committee meetings at 7:00 am and ended with Panel sessions that finished at 9:00 pm.

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IEEE CPMT Society Newsletter
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by email to nsltr-input@cpmt.org
..... Editor

President's Column (cont.):

Traditionally the CPMT Luncheon recognizes of achievements of many of our peers in the profession. We presented IEEE and CPMT Society awards recognized important and significant achievements and great contributions within our own community. We recognized best papers from CPMT transactions. This year, the Society created a new award, the CPMT Student Travel Award, which enabled sixteen students to participate in the ECTC Conference. It is an important message to the younger generation in our midst: the CPMT Society is their society and the ECTC conference is their conference.

This year we have started a tradition to honor and recognize the many dedicated volunteers in the ECTC program committees. Volunteers are the backbone of the ECTC, our Society and our profession. In this very difficult year, with the economy in trouble and the success of the ECTC in jeopardy, each and every one of the teams have worked long and hard to make this 59th conference the best ever.

Besides the professional development courses, panel sessions and technical programs, what does one do during ECTC? One of my favorite activities was the Best Practices Publication Workshop. It was held two times during the ECTC week. The workshop was led by Wayne Johnson, CPMT VP for Publications. The workshop is designed for those in our midst who do great research, make great presentations, and now want to write great technical papers and get them published in CPMT Transactions. In the workshop Wayne described the key attributes in a great journal paper and the best practices to achieve them. Developments in the electronic packaging industry are moving at a rapid and accelerating pace. It is crucially important to put one's significant research contribution into the best technical publications in our profession. Wayne will be holding the workshop at other CPMT Technical Conferences. Please be on the lookout for it.

ECTC is one of the many technical conferences in our global CPMT community. In my list of things to do is to complete the paper review assignment for EPTC conference in Singapore in December. In my own calendar for the month of August, there will be the ICEPT – HDP conference in Beijing, China, and the flexible electronics workshop in Binghamton NY. Please review the newsletter and the CPMT website for the complete listing.

The employment picture continues to be severe and daunting. In the spring message I mentioned that I expected deep downward trends for membership renewal and for new membership. Please pass the word out that for those of our members who have become unemployed they are eligible for 50% off IEEE and CPMT dues and subscriptions. They will be able to exercise this discount when it comes time to renew for 2010. This discount also applies to new membership as well. Additionally, IEEE has a number of career resources, including a job site listing to connect those who have jobs and who need jobs.

<http://www.ieee.org/web/careers/home/index.html>.

CPMT Society News:

**Congratulations to IEEE CPMT Society
Award Winners**

Presented at 59th ECTC in San Diego, CA

*Submitted by Leonard W. Schaper, Kitty Pearsall, and
Wayne Johnson*

CPMT Field Award:



The 2009 IEEE CPMT Award, the most prestigious award in the CPMT fields of study, was presented to GEORGE G. HARMAN (LF'IEEE) - NIST Scientist Emeritus (Retired NIST Fellow), Consultant, Gaithersburg, MD, USA, at the 2009 ECTC Conference.

The citation reads: "For pioneering achievements in wire bonding technology."

George Harman was hired at NBS/NIST in 1950 as an Electronic Scientist. In 1955, he filed for a patent on an electroluminescent microwave detector (# 2,928,937). He then studied the high frequency properties of various electroluminescent materials and discovered a new class of ferroelectric electroluminescent materials. His first 15 papers were generally in the area of applied physics and were published in the J. Appl. Physics, and similar journals. He studied contacts and surface states of several new unstudied (at that time) semiconductors (SiC, BC, etc.) and in the process obtained several US semiconductor device patents.